



Product Change Notification / RMES-09ZZXT280

Date:

02-Aug-2021

Product Category:

32-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4523 and 4523.001 Final Notice: Qualification of MTAI as an additional assembly site for selected ATSAMC20xx, ATSAMC21xx, ATSAMD20xx, ATSAMD21xx and ATSAMDA1xx device families available in 48L VQFN package.

Affected CPNs:

[RMES-09ZZXT280_Affected_CPN_08022021.pdf](#)

[RMES-09ZZXT280_Affected_CPN_08022021.csv](#)

Notification Text:

PCN Status:Final notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:Qualification of MTAI as an additional assembly site for selected ATSAMC20xx, ATSAMC21xx, ATSAMD20xx, ATSAMD21xx and ATSAMDA1xx device families available in 48L VQFN package.

Pre Change:

For wettable flank products:

Assembled at ASCL using gold (Au) bond wire, 8600 die attach, G700 molding compound material with 210 x 210 mils paddle size without locking holes leadframe.

or

Assembled at NSEB using gold (Au) or palladium coated copper wire with gold flash (CuPdAu) bond wire, EN-4900G or ATB-125 die attach, G700 molding compound material with 208 x 208 mils paddle size without locking holes leadframe.

or

Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound material with 217 x 217 mils paddle size with locking holes leadframe.

For non-wettable flank products:

Assembled at ASE using palladium coated copper wire with gold flash (CuPdAu) or palladium coated copper (PdCu) bond wire, EN-4900F die attach, G631H molding compound and C7025 leadframe material with 217 x 217 mils paddle size without locking holes.

or

Assembled at ASCL using palladium coated copper wire with gold flash (CuPdAu) bond wire, EN-4900GC die attach, G700 molding compound and C194 leadframe material with 210 x 210 mils paddle size without locking holes.

or

Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound and C194 leadframe material with 217 x 217 mils paddle size with locking holes leadframe.

Post Change:

For wettable flank products:

Assembled at ASCL using gold (Au) bond wire, 8600 die attach, G700 molding compound material with 210 x 210 mils paddle size without locking holes leadframe.

or

Assembled at NSEB using gold (Au) or palladium coated copper wire with gold flash (CuPdAu) bond wire, EN-4900G or ATB-125 die attach, G700 molding compound material with 208 x 208 mils paddle size without locking holes leadframe.

or

Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound material with 217 x 217 mils paddle size with locking holes leadframe.

or

Assembled at MTAI using gold (Au) bond wire, 3280 die attach, G700 molding compound material with 217 x 217 mils paddle size with locking holes leadframe.

For non-wettable flank products:

Assembled at ASE using palladium coated copper wire with gold flash (CuPdAu) or palladium coated copper (PdCu) bond wire, EN-4900F die attach, G631H molding compound and C7025 leadframe material with 217 x 217 mils paddle size without locking holes.

or

Assembled at ASCL using palladium coated copper wire with gold flash (CuPdAu) bond wire, EN-4900GC die attach, G700 molding compound and C194 leadframe material with 210 x 210 mils paddle size without locking holes.

or

Assembled at MMT using gold (Au) bond wire, 3280 die attach, G700 molding compound and C194 leadframe material with 217 x 217 mils paddle size with locking holes leadframe.

or

Assembled at MTAI using gold (Au) bond wire, 3280 die attach, G700 molding compound and C194 leadframe material with 217 x 217 mils paddle size with locking holes leadframe.

Pre and Post Change Summary:*For wettable flank products:*

	Pre Change			Post Change			
Assembly Site	ASE Group Chung-Li (ASCL)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand (Branch) / (MMT)	ASE Group Chung-Li (ASCL)	UTAC Thai Limited (UTL-1) LTD. (NSEB)	Microchip Technology Thailand (Branch) / (MMT)	Microchip Technology Thailand (HQ) (MTAI)
Wire material	Au	Au or CuPdAu	Au	Au	Au or CuPdAu	Au	Au
Die attach material	8600	EN-4900G or ATB-125	3280	8600	EN-4900G or ATB-125	3280	3280
Molding compound material	G700	G700	G700	G700	G700	G700	G700
Lead frame material	C194	C194	C194	C194	C194	C194	C194
Paddle size	210 x 210 mils	208 x 208 mils	217 x 217 mils	210 x 210 mils	208 x 208 mils	217 x 217 mils	217 x 217 mils
Lead Lock (Locking Holes)	No	No	Yes	No	No	Yes	Yes

For non-wettable flank products:

Assembly Site	ASE Inc. (ASE)	ASE Group Chung-Li (ASCL)	Microchip Technology Thailand (Branch) / (MMT)	ASE Inc. (ASE)	ASE Group Chung-Li (ASCL)	Microchip Technology Thailand (Branch) / (MMT)	Microchip Technology Thailand (HQ) (MTAI)
Wire material	CuPdAu or PdCu	CuPdAu	Au	CuPdAu or PdCu	CuPdAu	Au	Au
Die attach material	EN-4900F	EN-4900GC	3280	EN-4900F	EN-4900GC	3280	3280
Molding compound material	G631H	G700	G700	G631H	G700	G700	G700
Lead frame material	C7025	C194	C194	C7025	C194	C194	C194
Paddle size	217 x 217 mils	210 x 210 mils	217 x 217 mils	217 x 217 mils	210 x 210 mils	217 x 217 mils	217 x 217 mils
Lead Lock (Locking Holes)	No	No	Yes	No	No	Yes	Yes

Impacts to Data Sheet:None.

Change Impact:None.

Reason for Change:To improve on-time delivery performance by qualifying MTAI as an additional assembly site.

Change Implementation Status:In Progress

Estimated First Ship Date:August 23, 2021 (date code: 2135)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	February 2021				>	August 2021				
Workweek	06	07	08	09		32	33	34	35	36
Initial PCN Issue Date				X						
Qual Report Availability						X				
Final PCN Issue Date										
Estimated Implementation Date									X	

Method to Identify Change:Traceability code

Qualification Report:Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

February 25, 2021: Issued initial notification.

August 2, 2021: Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on August 23, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_RMES-09ZZXT280_Pre and Post Change Summary.pdf](#)

[PCN_RMES-09ZZXT280 Qual Report.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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